Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP 1920-48G Switch

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		766
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		27
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle and then remove mounting angle 12.
2. Remove the cover 6
3. Remove all of the inner cables.
4. Unscrew the screws on PCB 4, and then remove PCB 4
5. Unscrew the screws on PCB 7, and then remove PCB 7
6. Unscrew the screws on PCB 8, and then remove PCB 8
7. insulate plate 3 and outlet 10
8. Remove film 2 from panel 11
9. Remove film 1 from panel 2
10. Remove all of the labels.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

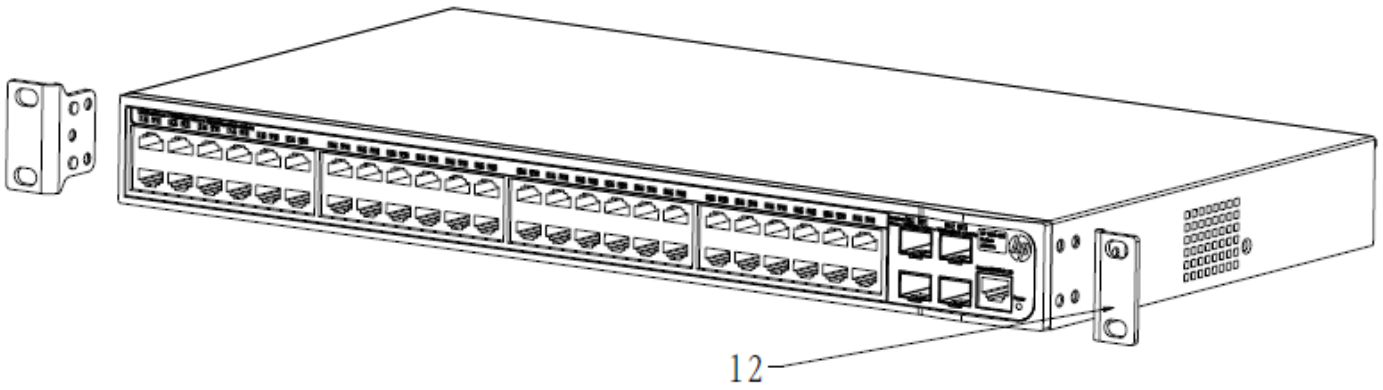

Figure1 Remove mounting angle

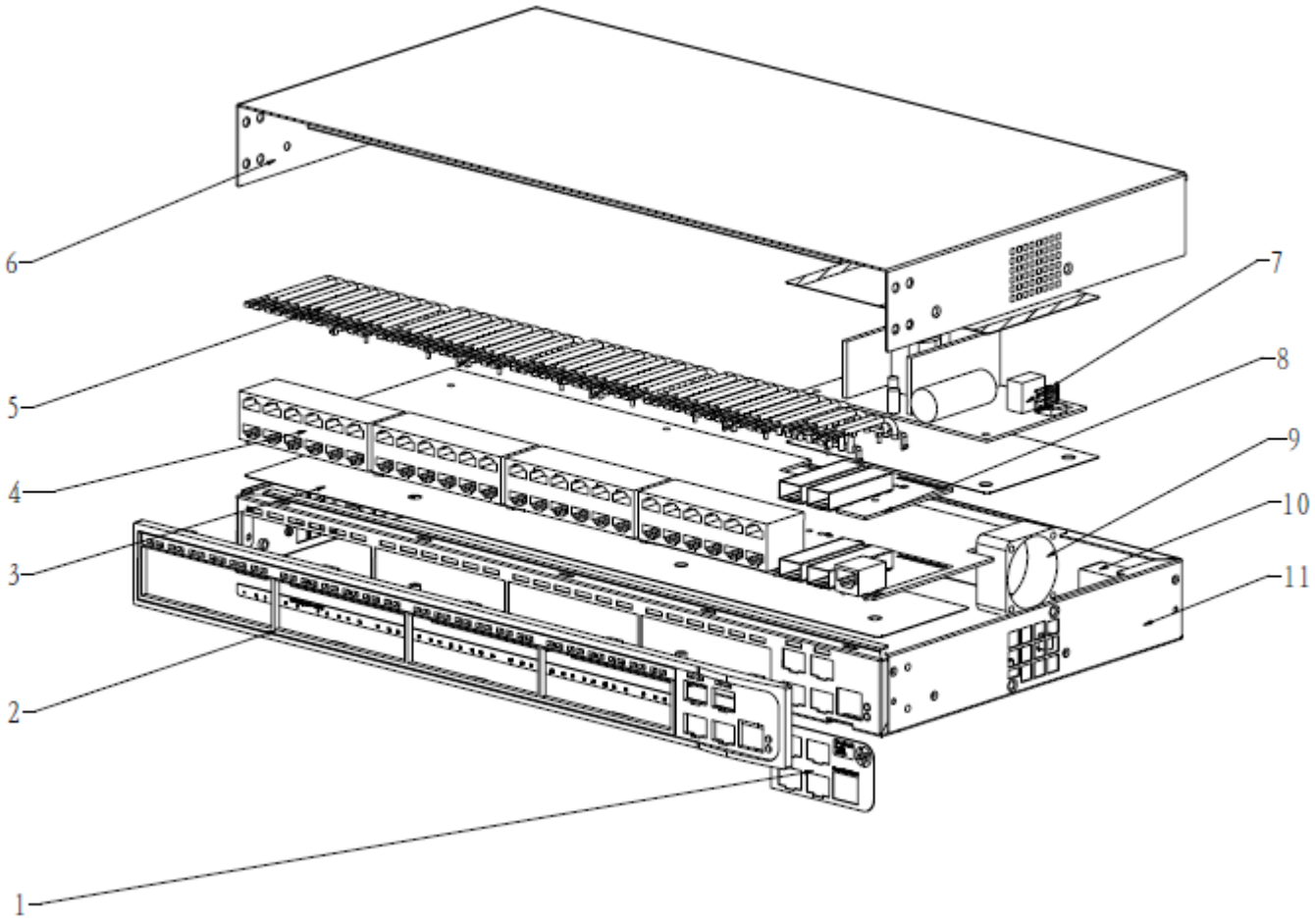

Figure2 Treatment to the product

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1.	Film	PC	5	0.16%	Containing brominated flame retardants	
2	Plastic panel	PC	30	1.01%	Containing brominated flame retardants	
3.	insulating panel	PC	8	0.2%	The surface of PCB is greater than 10 square centimeters	
4	Main board	Complex PCB	812	27.4%	The surface of PCB is greater than 10 square centimeters	
5	Light pipe	PC	36	1.21%	The surface of PCB is greater than 10 square centimeters	
6	Top case	Fe	915	30.8%		Fe recycling
7	Power PCB	Complex PCB	204	6.8%	Containing brominated flame retardants	
8	Gusset plate	Complex PCB	34	1.1%	The surface of PCB is greater than 10 square centimeters	
9	Electric fan	ABS	22	0.9%	Containing brominated flame retardants	
10	AC power jack	PC	16	0.7%	Containing brominated flame retardants	
11	Bottom case	Fe	851	28.7%		Fe recycling
12	Mount angle	Fe	32	1.02%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2014.07.31	V0	Zhang Hongrui	Initial version